PCN Number:	202	20240408003.2			PCN Date:		April 12, 2024		
Title: Datasheet for DLPC23x-Q1 and DLPC23xS-Q1									
Customer Contact: Change			ge Management			Dept:		Quality Services	
Proposed 1 st Ship Date: Oct				October 09, 2024					
Change Type:									
Assembly Site			Design				Wafer Bump Site		
Assembly Process			□ Data Sheet				Wafer Bump Material		
Assembly Materials			Part number change				Wafer Bump Process		
Mechanical Specification			Test Site				Wafer Fab Site		
Packing/Shipping/Labeling				Test Process			Wafer Fab Materials		
Wafer Fab Process								Fab Process	
Notification Details									

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.



DLPC230-Q1, DLPC231-Q1 DLPS054H – DECEMBER 2015 – REVISED MARCH 2024

C	hanges from Revision G (September 2023) to Revision H (March 2024)	Page
•	Updated section for inclusive terminology; Added note to Table 4-10	3
•	Changed ESD Ratings table to the automotive format; added ESD Ratingsspec for ZEK package	15
•	Removed "Advanced Information" comment; Updated footnote 2 example	16
•	Updated Max current values for VCC1.1 and VCC1.8 total and each supply input	17
•	Updated Package - Maximum Power	21
•	Updated Section 5.20 for inclusive terminology	31
•	Updated Section 5.21 section for inclusive terminology	
•	Updated Section 7.3.9 for inclusive terminology	48
•	Updated Section 7.3.10 for inclusive terminology	
•	Added Layout examples	65
•	Added DLPC231 Device Markings	66
•	Updated ZDQ0324A package outline to show alternate mold dimension; Added ZEK0324A package	outline
	drawing to support DLPC231-Q1 and DLPC231S-Q1	70
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DLPC230S-Q1, DLPC231S-Q1 DLPS201D - AUGUST 2020 - REVISED MARCH 2024

Changes from Revision C	(September 20	23) to Revisio	on D (March 2024)		Page					
Changes from Revision C (September 2023) to Revision D (March 2024) Updated section for inclusive terminology; Added note to Table 4-10										
	Changed ESD Ratings table to the automotive format; added ESD Ratingsspec for ZEK package									
Removed "Advanced Information" comment; Updated footnote 2 example										
Updated Max current values for VCC1.1 and VCC1.8 total and each supply input										
Updated Package - Maximum Power										
 Updated Section 5.20 for 	Updated Section 5.20 for inclusive terminology									
Updated Section 5.21 for inclusive terminology										
Updated Section 7.3.9 for inclusive terminology										
Updated Section 7.3.10 for inclusive terminology										
Added DLPC231 Device Markings64										
 Updated ZDQ0324A package outline to show alternate mold dimension.; Added ZEK0324A package outline 										
drawing to support DLPC231-Q1 and DLPC231S-Q167										
The datasheet number w	الله مما النا	. ~								
The datasheet number w	ili be changin	-		CI	-					
Device Family	Pevice Family Change From: Change To:									
DLPC23x-Q1		DLPS054G		DLPS	6054H					
DLPC23xS-Q1		DLPS201C		DLPS201D						
These changes may be re			links provided.							
http://www.ti.com/product/DLPC230TZDQQ1										
http://www.ti.com/product/DLPC230STZDQQ1										
Reason for Change:										
To accurately reflect devi	ce characteri	stics.								
Anticipated impact on	Fit Form F	unction O	ıality or Reliabili	ty (no	ositive / negative):					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): Electrical specification performance changes as indicated above.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
DLPC230TZDQQ1	DLPC230TZD	QRQ1	DLPC231ZEKQ1 DLPC231ZEK		DLPC231ZEKRQ1					
DLPC230STZDQQ1	DLPC231SZEK	<u> </u>	`		DLPC23STZDQRQ1					
DLI CZ5051ZDQQ1	DEI CZUIJZEN	· · · ·	DLI CZOTSZLIMQT		DEI CZOSTZDQNQ1					

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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